

1 **ABSTRACT OF THE DISCLOSURE**

2 A method of engaging electrically conductive test pads on a
3 semiconductor substrate having integrated circuitry for operability testing
4 thereof includes: a) providing an engagement probe having an outer
5 surface comprising a grouping of a plurality of electrically conductive
6 projecting apexes positioned in proximity to one another to engage a
7 single test pad on a semiconductor substrate; b) engaging the grouping
8 of apexes with the single test pad on the semiconductor substrate; and
9 c) sending an electric signal between the grouping of apexes and test
10 pad to evaluate operability of integrated circuitry on the semiconductor
11 substrate. Constructions and methods are disclosed for forming testing
12 apparatus comprising an engagement probe having an outer surface
13 comprising a grouping of a plurality of electrically conductive projecting
14 apexes positioned in proximity to one another to engage a single test
15 pad on a semiconductor substrate.